



## PJQ5948-AU

### 40V Dual N-Channel Enhancement Mode MOSFET

Voltage      40 V      Current      37 A

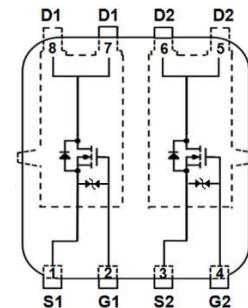
#### Features

- $R_{DS(ON)}$ ,  $V_{GS}=10V$ ,  $I_D=10A < 12.3m\Omega$
- $R_{DS(ON)}$ ,  $V_{GS}=4.5V$ ,  $I_D=6A < 15.7m\Omega$
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

#### Mechanical Data

- Case : DFN5060B-8L Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.092 grams

DFN5060B-8L



#### Maximum Ratings and Thermal Characteristics ( $T_A=25^\circ C$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNITS
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current <sup>(Note 3)</sup>	$I_D$	37	A
		26	
Pulsed Drain Current <sup>(Note 1)</sup>	$I_{DM}$	148	W
Power Dissipation	$P_D$	30	
		15	
Continuous Drain Current <sup>(Note 4)</sup>	$I_D$	10.6	A
		9	
Power Dissipation	$P_D$	2.5	W
		1.8	
Single Pulse Avalanche Energy <sup>(Note 5)</sup>	$E_{AS}$	42	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~175	°C
Thermal Resistance <sup>(Note 4)</sup>	Junction to Case	$R_{\theta JC}$	5
	Junction to Ambient	$R_{\theta JA}$	60
			°C/W



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### Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
<b>Static</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	40	-	-	V
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=50\mu\text{A}$	1.1	1.6	2.3	
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{on})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=10\text{A}$	-	9.8	12.3	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=6\text{A}$	-	12.1	15.7	
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=40\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
		$\text{V}_{\text{GS}}=\pm 10\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm 1$	
<b>Dynamic</b> <sup>(Note 6)</sup>						
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=32\text{V}, \text{I}_D=10\text{A}, \text{V}_{\text{GS}}=10\text{V}$	-	13	-	$\text{nC}$
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	3	-	
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	2	-	
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=25\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1\text{MHz}$	-	778	-	$\text{pF}$
Output Capacitance	$\text{C}_{\text{oss}}$		-	180	-	
Reverse Transfer Capacitance	$\text{Crss}$		-	25	-	
Gate resistance	$\text{R}_g$	$\text{f}=1\text{MHz}$	-	1.6	-	$\Omega$
Turn-On Delay Time	$\text{t}_{\text{d}(\text{on})}$	$\text{V}_{\text{DS}}=32\text{V}, \text{I}_D=10\text{A}, \text{V}_{\text{GS}}=10\text{V}, \text{R}_g=3\Omega$ <small>(Note 2)</small>	-	9	-	$\text{ns}$
Turn-On Rise Time	$\text{t}_r$		-	3	-	
Turn-Off Delay Time	$\text{t}_{\text{d}(\text{off})}$		-	21	-	
Turn-Off Fall Time	$\text{t}_f$		-	3	-	
<b>Drain-Source Diode</b>						
Diode Forward Current	$\text{I}_s$	$\text{T}_{\text{C}}=25^\circ\text{C}$	-	-	37	$\text{A}$
Pulsed Diode Forward Current	$\text{I}_{\text{SM}}$		-	-	148	
Diode Forward Voltage	$\text{V}_{\text{SD}}$	$\text{I}_s=20\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	0.9	1.3	$\text{V}$
Reverse Recovery Time	$\text{Tr}_{\text{r}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=20\text{A}$ $d\text{I}_s/dt=100\text{A}/\mu\text{s}$	-	21	-	$\text{ns}$
Reverse Recovery Charge	$\text{Q}_{\text{rr}}$		-	10	-	

#### NOTES :

1. Pulse width  $\leq 100\mu\text{s}$ , Duty cycle  $\leq 2\%$ .
2. Essentially independent of operating temperature typical characteristics.
3. Chip capability with an  $R_{\text{eJC}}=5^\circ\text{C}/\text{W}$ .
4.  $R_{\text{eJA}}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
5. The test condition is  $L=0.5\text{mH}, \text{I}_{\text{AS}}=13\text{A}, \text{V}_{\text{DD}}=30\text{V}, \text{V}_{\text{GS}}=10\text{V}$ , Starting  $\text{T}_j=25^\circ\text{C}$ .
6. Guaranteed by design, not subject to production testing.



## PJQ5948-AU

### TYPICAL CHARACTERISTIC CURVES

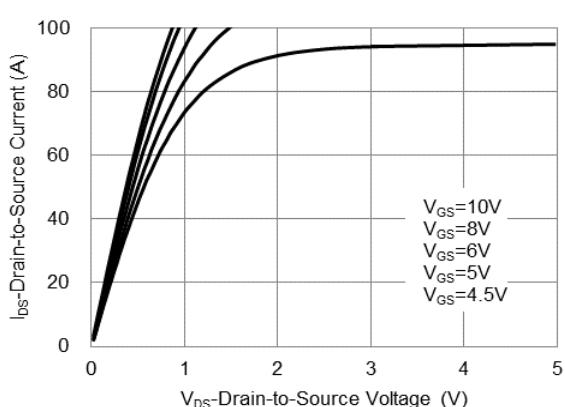


Fig.1 On-Region Characteristics

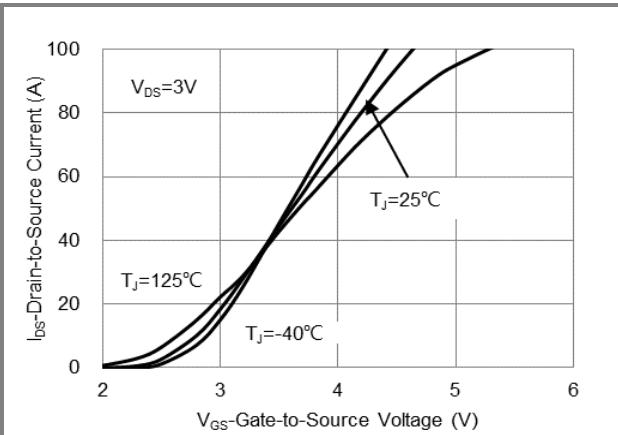


Fig.2 Transfer Characteristics

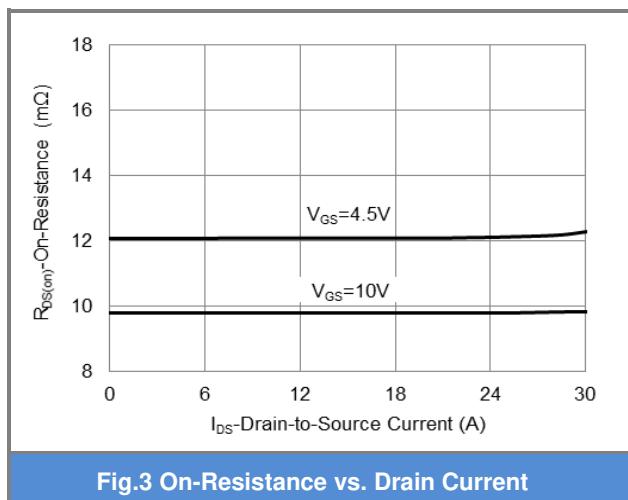


Fig.3 On-Resistance vs. Drain Current

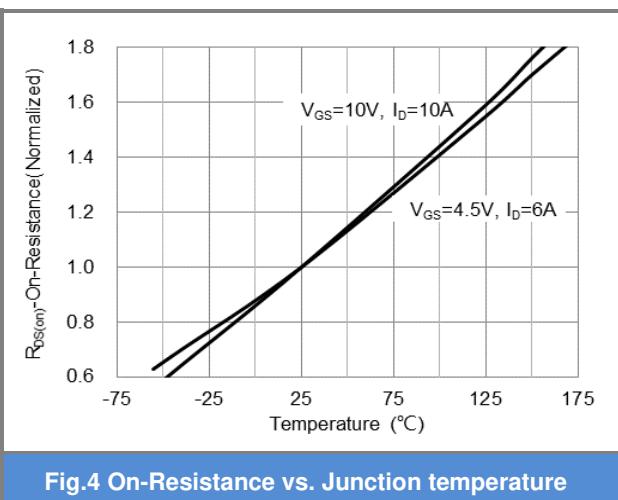


Fig.4 On-Resistance vs. Junction temperature

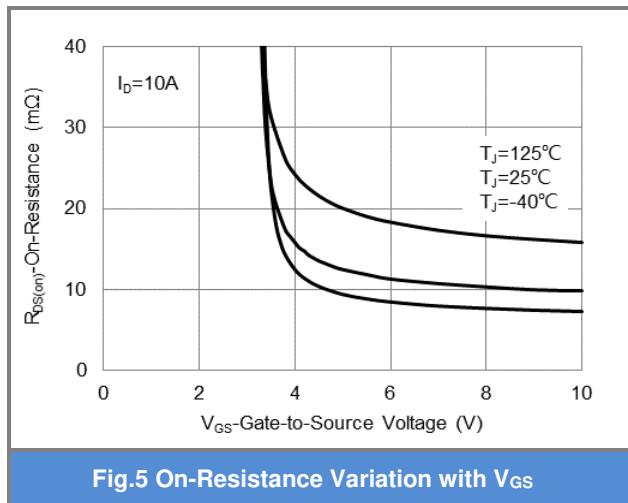


Fig.5 On-Resistance Variation with Vgs

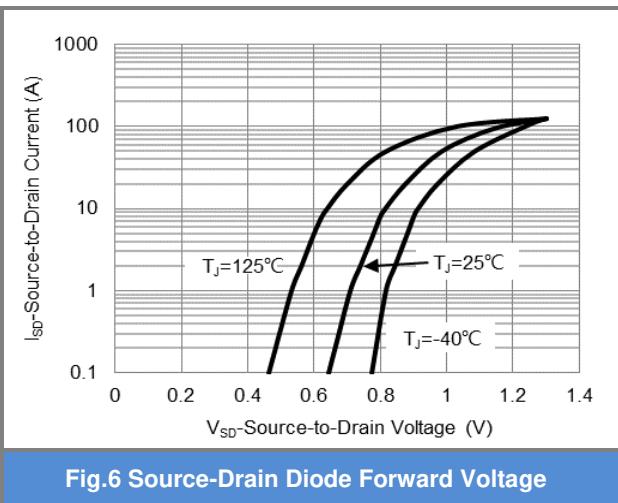


Fig.6 Source-Drain Diode Forward Voltage



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### TYPICAL CHARACTERISTIC CURVES

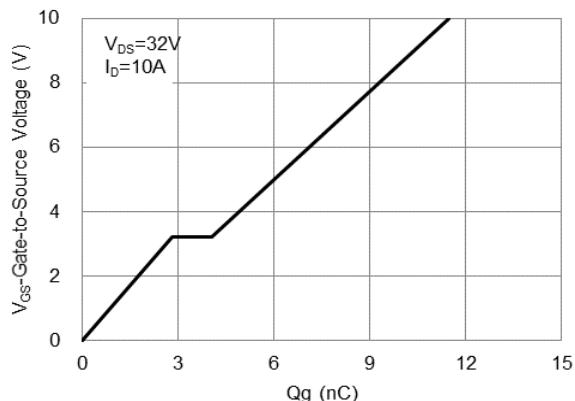


Fig.7 Gate-Charge Characteristics

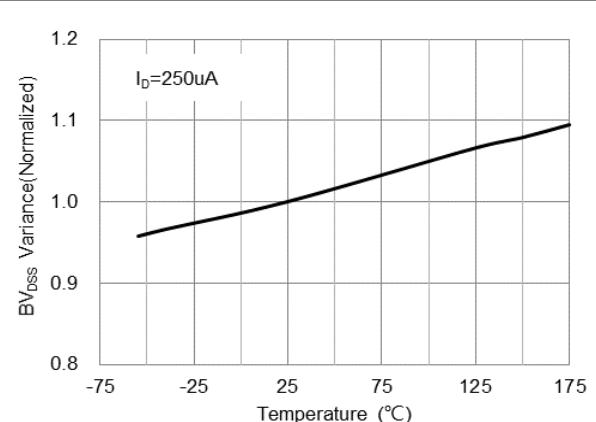


Fig.8 Breakdown Voltage Variation vs. Temperature

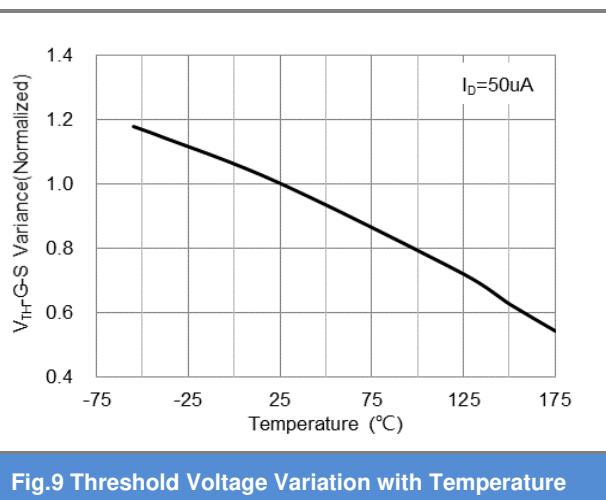


Fig.9 Threshold Voltage Variation with Temperature

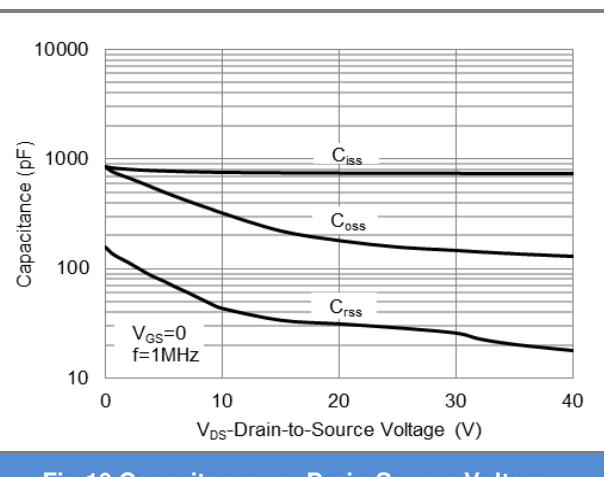


Fig.10 Capacitance vs. Drain-Source Voltage

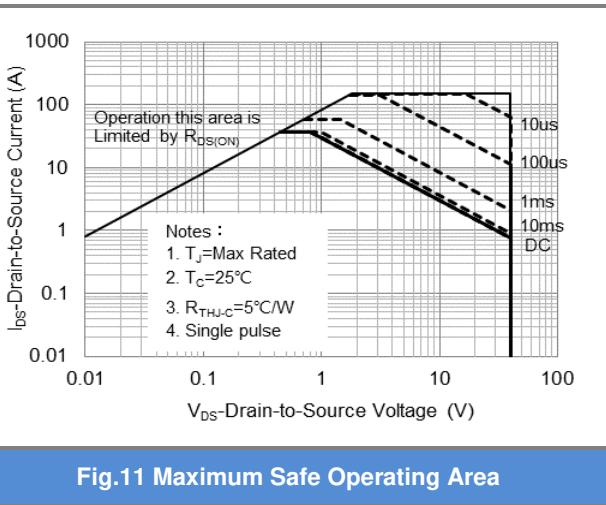


Fig.11 Maximum Safe Operating Area

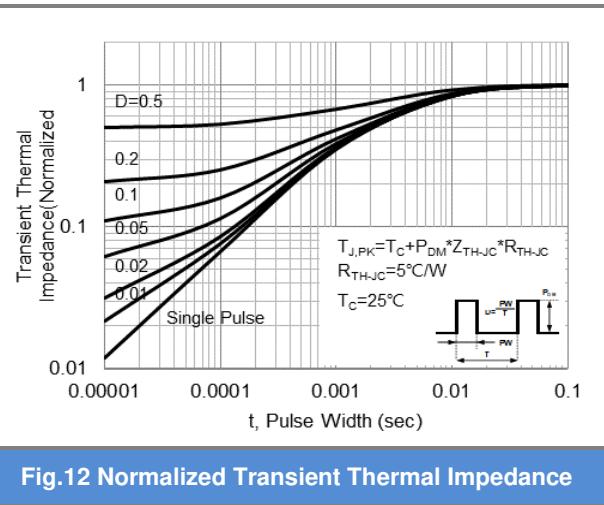


Fig.12 Normalized Transient Thermal Impedance

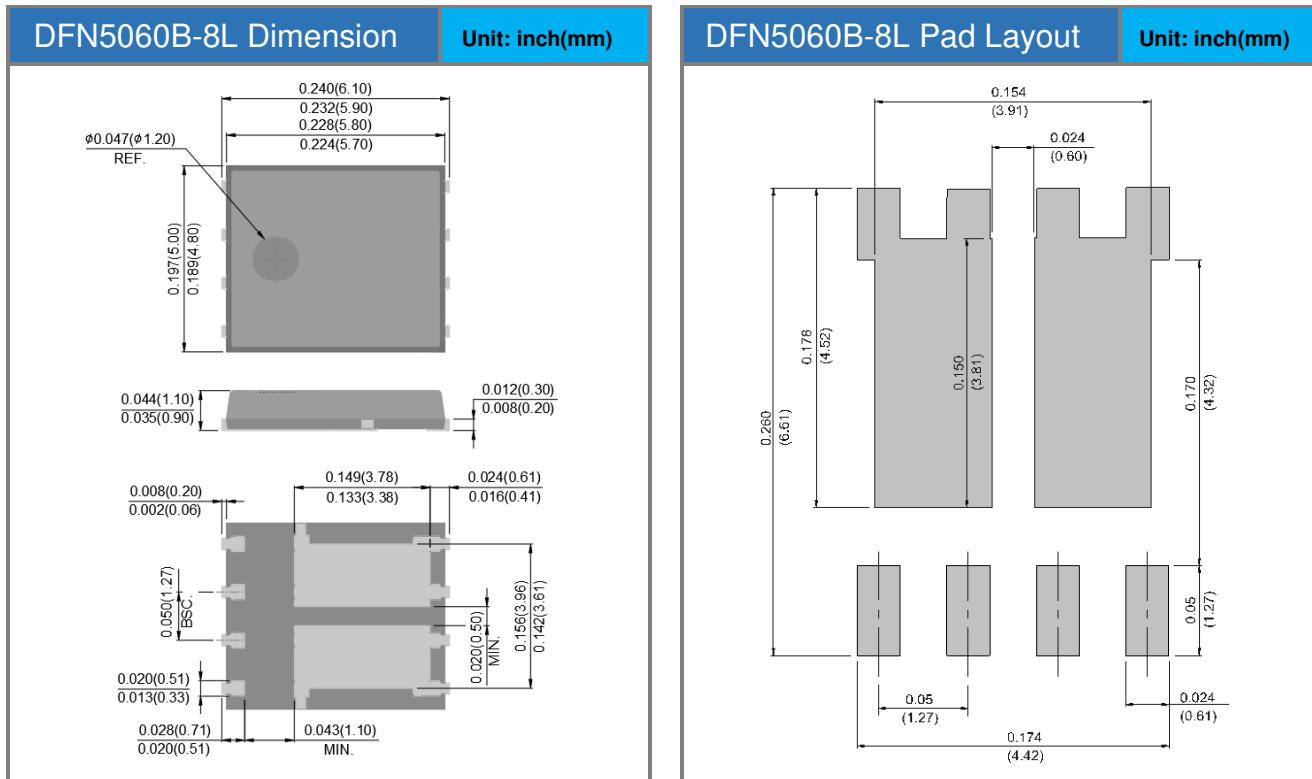


## PJQ5948-AU

### Product and Packing Information

Part No.	Package Type	Packing Type	Marking
PJQ5948-AU	DFN5060B-8L	3K pcs / 13" reel	Q5948

### Packaging Information & Mounting Pad Layout





## **PJQ5948-AU**

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